

# LUP12N65 / LUF12N65

650V N-Channel Enhancement Mode MOSFET

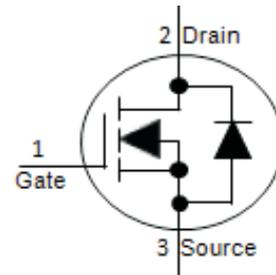
## Product General Description

These enhancement mode power field effect transistors have been advanced technology design to provide low on-state resistance, high avalanche energy. These devices are well suited for popular AC-DC applications, active power factor correction, ballasts based on half-bridge topology.

## Features

**12A , 650V,  $R_{DS(ON)}=0.8\Omega@V_{GS}=10V, I_D=6.0A$**

- Low On-state Resistance
- Fast Switching
- Low Gate Charge
- Fully Characterized Avalanche Voltage and Current



## Marking and Order Information

TYPE	MARKING	PACKAGE	PACKING
LUP12N65	P12N65	TO-220	50PCS/TUBE
LUF12N65	F12N65	TO-220F	50PCS/TUBE

## Absolute Maximum Ratings and Thermal Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	ULP12N65	ULF12N65	Units
Drain-Source Voltage	$V_{DS}$	650		V
Gate-Source Voltage	$V_{GS}$	$\pm 30$		V
Continuous Drain Current	$I_D$	12	12	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	48	48	A
Avalanche Energy with Single Pulse $I_{AS}=12A, V_{DD}=90V, L=12mH$	$E_{AS}$	990		mJ
Maximum Power Dissipation Derating Factor	$P_D$	175 1.4	52 0.42	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150		$^\circ\text{C}$
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	0.7	2.4	$^\circ\text{C/W}$
Junction-to Ambient Thermal Resistance	$R_{\theta JA}$	62.5	100	$^\circ\text{C/W}$

**Note** : 1. Maximum DC current limited by the package

**IMPROVE PRODUCT DESIGN,FUNCTIONS AND RELIABILITY WITHOUT NOTICE**

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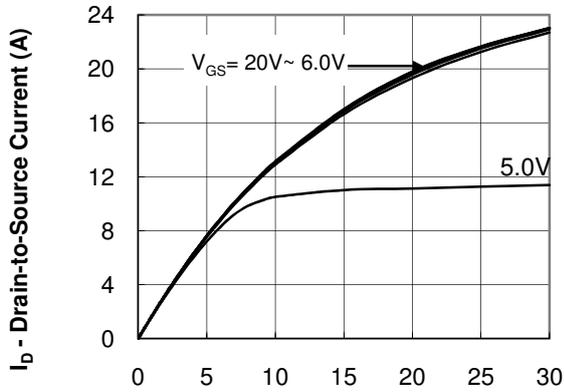
650V N-Channel Enhancement Mode MOSFET

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Units
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	-	4.0	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=6.0A$	-	0.66	0.8	$\Omega$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$	-	-	10	$\mu A$
Gate Body Leakage	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=520V, I_D=12A,$ $V_{GS}=10V$	-	46.8	62	nC
Gate-Source Charge	$Q_{gs}$		-	9.2	-	
Gate-Drain Charge	$Q_{gd}$		-	14.6	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=325V, I_D=12A$ $V_{GS}=10V, R_G=25\Omega$	-	16.2	24	ns
Turn-On Rise Time	$t_r$		-	26.8	42	
Turn-Off Delay Time	$t_{d(off)}$		-	56	98	
Turn-Off Fall Time	$t_f$		-	24.6	38	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V$ $f=1.0MHz$	-	1800	2450	pF
Output Capacitance	$C_{oss}$		-	145	195	
Reverse Transfer Capacitance	$C_{rss}$		-	16	22	
<b>Source-Drain Diode</b>						
Max. Diode Forward Current	$I_S$	-	-	-	12	A
Max.Pulsed Source Current	$I_{SM}$	-	-	-	48	A
Diode Forward Voltage	$V_{SD}$	$I_S=12A, V_{GS}=0V$	-	-	1.4	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_F=12A$ $di/dt=100A/us$	-	450	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	5.0	-	$\mu C$

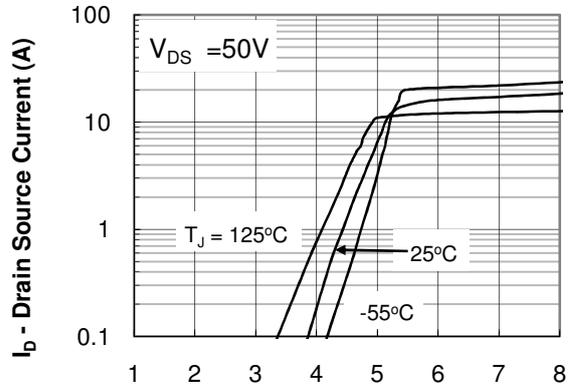
**NOTE** : Plus Test : Pluse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .

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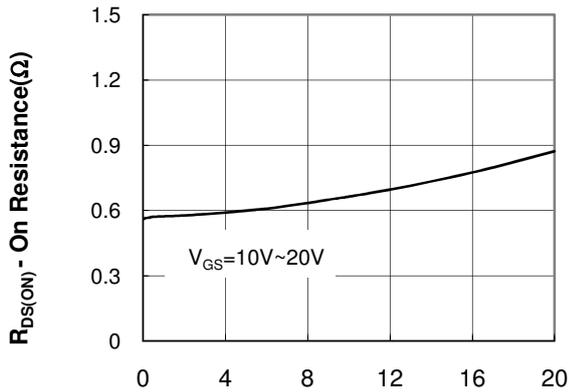
Typical Characteristics Curves (  $T_c=25^\circ\text{C}$ , unless otherwise noted)



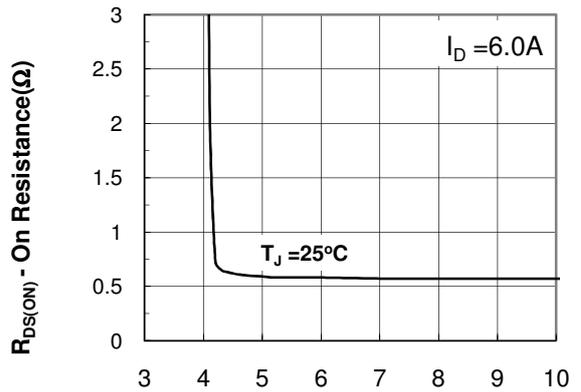
$V_{DS}$  - Drain-to-Source Voltage (V)  
**Output Characteristic**



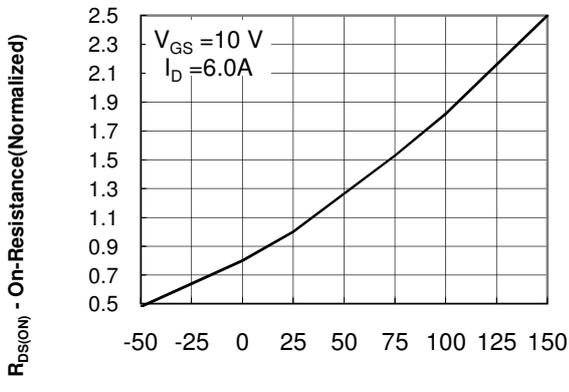
$V_{GS}$  - Gate-to-Source Voltage (V)  
**Transfer Characteristic**



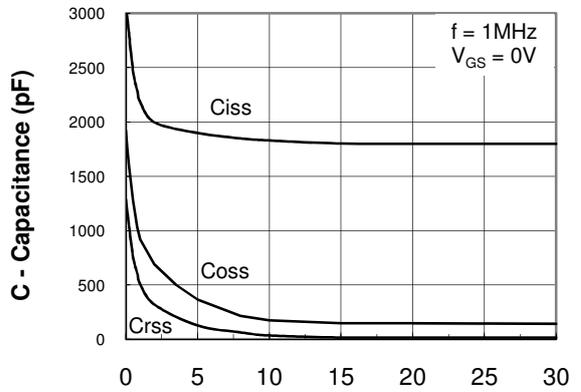
$I_D$  - Drain Current (A)  
**On Resistance vs Drain Current**



$V_{GS}$  - Gate-to-Source Voltage (V)  
**On Resistance vs Gate to Source Voltage**



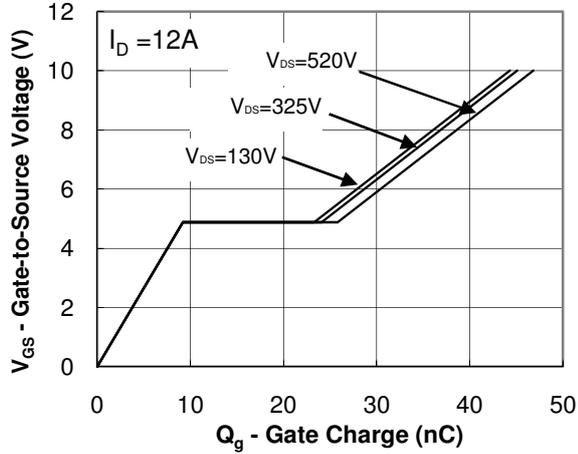
$T_J$  - Junction Temperature ( $^\circ\text{C}$ )  
**On Resistance vs Junction Temperature**



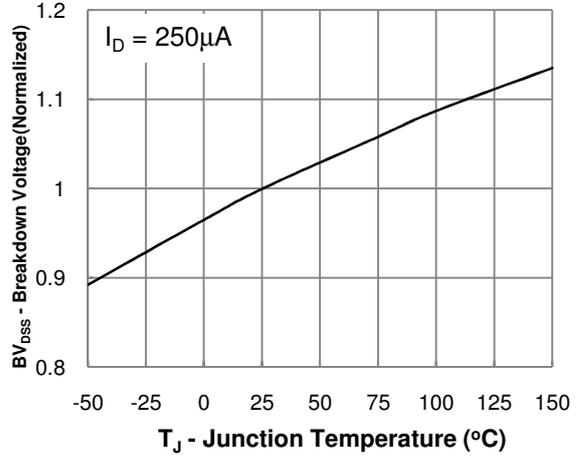
$V_{DS}$  - Drain-to-Source Voltage (V)  
**Capacitance**

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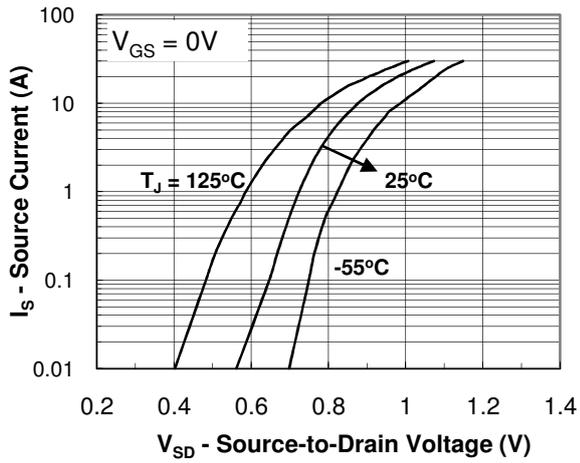
Typical Characteristics Curves (  $T_c=25^\circ\text{C}$ , unless otherwise noted)



Gate Charge Waveform



Breakdown Voltage vs Junction Temperature



Source-Drain Diode Forward Voltage